

Gary Tressler, Tom Griffin and Patrick Breen IBM Corporation



<u>Agenda</u>

- Industry Trend
- Background
- Mixed Mode Analysis
- Influence of Environment / Flash Access Mode
- Read Disturb Tolerance vs. Technology
- MLC Read Cycling Analysis
- Initial TLC Analysis
- Dynamic Analysis
- Summary



Read Disturb – Industry Trend

- With technology advancement, Flash industry began to make tradeoffs to maintain endurance levels
 - Read disturb tolerances were reduced in some cases
- Read intensive Flash applications have increased focus on read disturb failure mechanism
- Growth and application of TLC have also highlighted read disturb tolerance as a key specification
- Traditionally, read disturb specifications are not widely available in supplier data sheets
- NET: Based on technology advancement, emergence of read intensive applications and TLC, read disturb tolerances must be thoroughly evaluated and better understood



Read Disturb – Background

- Read disturb occurs when programmed blocks are read repeatedly without any erases in between these reads
 - When one wordline is read, other wordlines in the block are weakly programmed (V_{pass} applied)
 - Repeated reads without an erase can cause cells to shift enough to change their state
 - Read disturb effect is exacerbated by P/E cycling stress
 - Block erase resets read disturb effect
- JEDEC read disturb test specification is to read all pages in a Flash block sequentially
- Read disturb effects are more pronounced in smaller technology nodes





Mixed Mode Analysis



2 PE Cycles Inserted Between 30K Read Cycle Runs (3002 PE Cycles Total)

3K PE Cycles Inserted Between 30K Read Cycle Runs (6K PE Cycles Total)

- Experiment confirms
 - PE cycling stress worsens read disturb effect
 - Block erase resets read disturb effect
 - Read cycling interspersed between PE cycles does not affect wear rate



Note:

Read Disturb Characterization for Next-Generation Flash Systems

MLC Read Cycling – Address Sequencing Analysis





Read Disturb Performance – Technology Progression



Supplier Z: Post 3K PE cycling, 30K Read cycling (80/20% PE cycling @ 59.2'C, Read cycling @ 40'C)

- Notable degradation of MLC read cycle performance with technology progression
 - 1znm read error rate is 1.5 orders of magnitude worse than 3xnm
 - However, resulting read error rate also driven by degradation in PE cycle capability vs. technology

Santa Clara, CA

- August 2015 •
- 1znm read cycle tolerance is slightly improved from prior generation
- 3D NAND expected to provide temporary relief of read disturb effects, but further degradation must be monitored



MLC Read Cycling Analysis



Nominal - No Read Optimization Optimal - Read Optimization

• Read cycling BER acceleration (post 10K PE cycling) is more prominent in upper pages

- Read cycling BER accelerates at higher rate after 10K PE cycles (relative to 3K PE cycles)
- Indication of increased wear due to PE cycling contributing to higher Read Cycling BER





Initial TLC Analysis



Supplier K (TLC): Post-3600-PE Cycling, 100K Read Cycling (Non-Accelerated PE Cycling @59.2C, Read Cycling @40C)

- Initial TLC analysis shows solid read cycling BER performance (relative to PE cycling)
- May be an appropriate design point for read intensive applications
- Minimal gain observed with read level optimization for both PE cycling and read cycling



August 2015



Summary

- With the emergence of read intensive applications and TLC, the Flash read disturb failure mechanism must be thoroughly evaluated and well understood
- Read disturb effects are more pronounced with the progression of technology groundrules
- Initial TLC read disturb tolerance analysis looks promising
- Dynamic Flash operations require careful consideration of read disturb effects
- Read disturb tolerance specifications must be documented in supplier Flash component data sheets



Thank You

Gary Tressler IBM Corporation gtressle@us.ibm.com